Copper Layer Count: 2 Board Thickness: 1.6000 mm

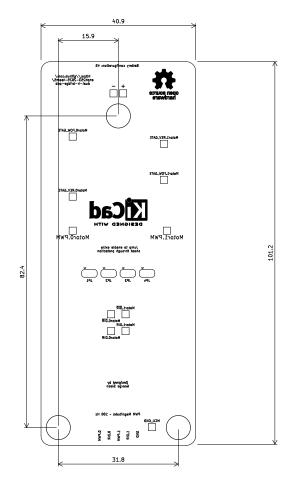
Board overall dimensions: $40.8940 \text{ mm} \times 101.4730 \text{ mm}$

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



George Sleer	n				
Team 5					
Sheet:					
File: dual-h-bridge.kicad_pcb					
Title: Dua	l H–Bridge			11	
Size: A4	Date: 2025-07-09		Rev: v4.0.0	٦ ا	

KiCad E.D.A. 9.0.3 Id: 1/4

Copper Layer Count: Board Thickness: 1.6000 mm

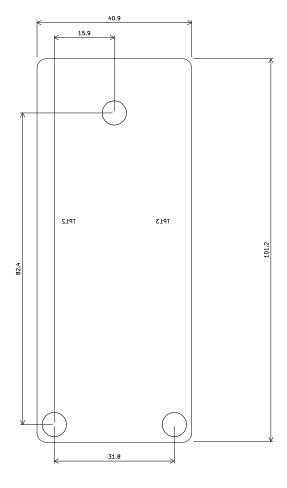
Board overall dimensions: $40.8940 \text{ mm} \times 101.4730 \text{ mm}$

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: Plated Board Edge: No No

Edge card connectors: Νo

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



George Sleen

Team 5

Sheet:

File: dual-h-bridge.kicad_pcb

Title: Dual H-Bridge

Size: A4 Date: 2025-07-09 Rev: v4.0.0 KiCad E.D.A. 9.0.3

ld: 2/4

Copper Layer Count: 2 Board Thickness: 1.6000 mm

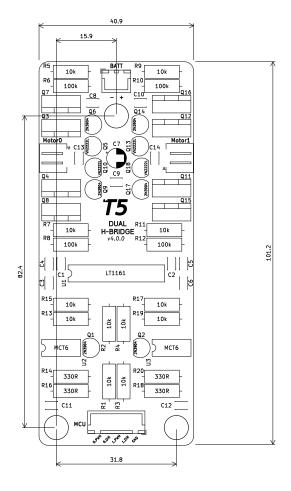
Board overall dimensions: $40.8940 \text{ mm} \times 101.4730 \text{ mm}$

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



George Sleen
Team 5
Sheet:
File: dual-h-bridge.kicad_pcb

Title: Dual H-Bridge

 Size: A4
 Date: 2025-07-09
 Rev: v4.0.0

 KiCad E.D.A. 9.0.3
 Id: 3/4

Copper Layer Count: 2 Board Thickness: 1.6000 mm

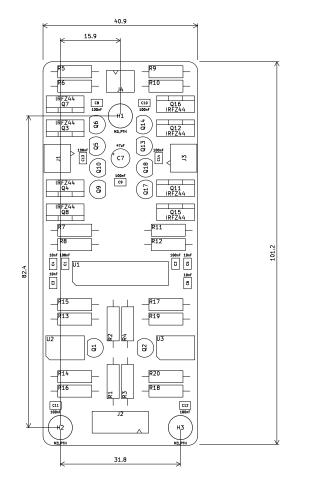
Board overall dimensions: $40.8940 \text{ mm} \times 101.4730 \text{ mm}$

Min track/spacing: 0.1000 mm / 0.1000 mm Min hole diameter: 0.2500 mm

Copper Finish: None Impedance Control: No Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.51 mm	Not specified	4.5	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



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Team 5			
Sheet:			1
File: dual-h-	-bridge.kicad_pcb		
Title: Dual	l H–Bridge		1
Size: A4	Date: 2025-07-09	Rev: v4.0.0	7
KiCad E.D.A. 9.0.3		ld: 4/4	٦

7